

Specification of Electret Condenser Microphone (RoHS Compliance&Halogen-Free)

Customer Name :
Customer Model :
GoerTek Model : B4013AM423-098

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Restricted

1 Security warning

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2 Publication history

Version	Date	Description	Design	Approval
1.0	2018.07.04	New Design	Jery. Yang	Near.An

3 Symbols Show

Symbols	Show
©	Signify Customer's Special Characteristic.
Ⓒ	Signify GoerTek Special Characteristic.

Contents

1	Test Condition	4
2	Electrical Characteristics	4
3	Frequency Response Curve and Limits	4
4	Measurement Circuit	5
5	Test setup Drawing	5
6	Mechanical Characteristics	6
6.1	Appearance Drawing	6
6.2	Weight	6
7	Structure of SMD MIC	7
8	Reliability Test	8
8.1	Vibration Test	8
8.2	Drop Test	8
8.3	Temperature Test	8
8.4	Humidity Test	8
8.5	Temperature Cycle Test	8
8.6	Temperature Shock Test	8
8.7	ESD Shock Test	8
8.8	Reflow Test	8
9	Package	9
9.1	Taping Specification	9
9.2	Reel Dimension	10
9.3	The content of box(13" reel)	10
9.4	Packing Explain	11
10	Stock and Transportation	11
11	Land Pattern Recommendation	12
11.1	Soldering Surface - Land Pattern	12
11.2	Metal Mask Pattern	12
12	Recommend Soldering	13
12.1	Soldering Machine Condition	13
12.2	The pattern of the nozzle	13
12.3	Reflow Profile	14
13	Cautions when using SMD MIC	15
13.1	X-ray inspection	15
13.2	Board wash restrictions	15
13.3	Nozzle restrictions	15
13.4	Others restrictions	15
14	Output Inspection standard	15

PRODUCT SPECIFICATIONS

Type : Electret Condenser Microphone

Model: B4013AM423-098

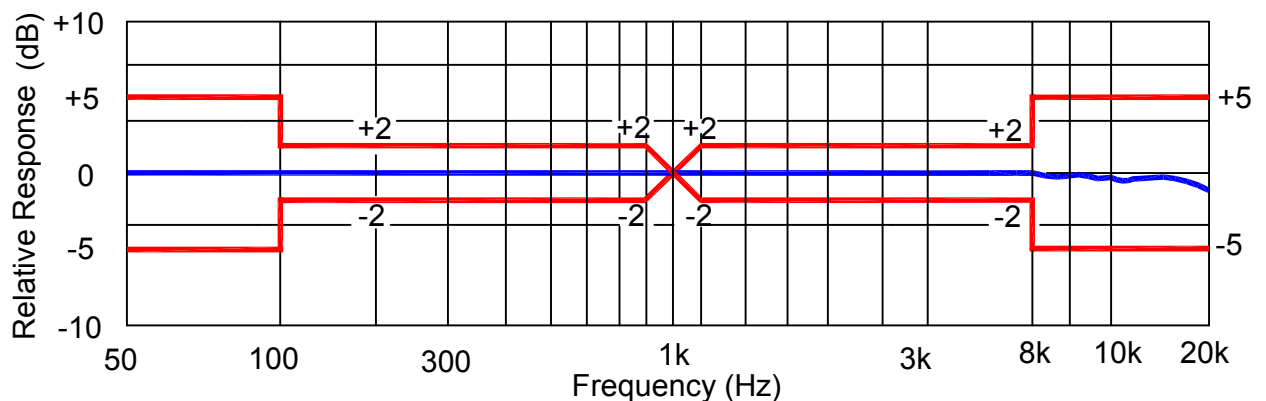
1 Test Condition (Vs=2.0V , RL=2.2kΩ, L=50cm)

Standard Conditions (Re. IEC 60268-4)	Temperature	Humidity	Air pressure
Environment Conditions	+15°C~+35°C	25%RH~75%RH	86kPa~106kPa
Judgement Conditions	+20°C±2°C	60%RH~70%RH	86kPa~106kPa

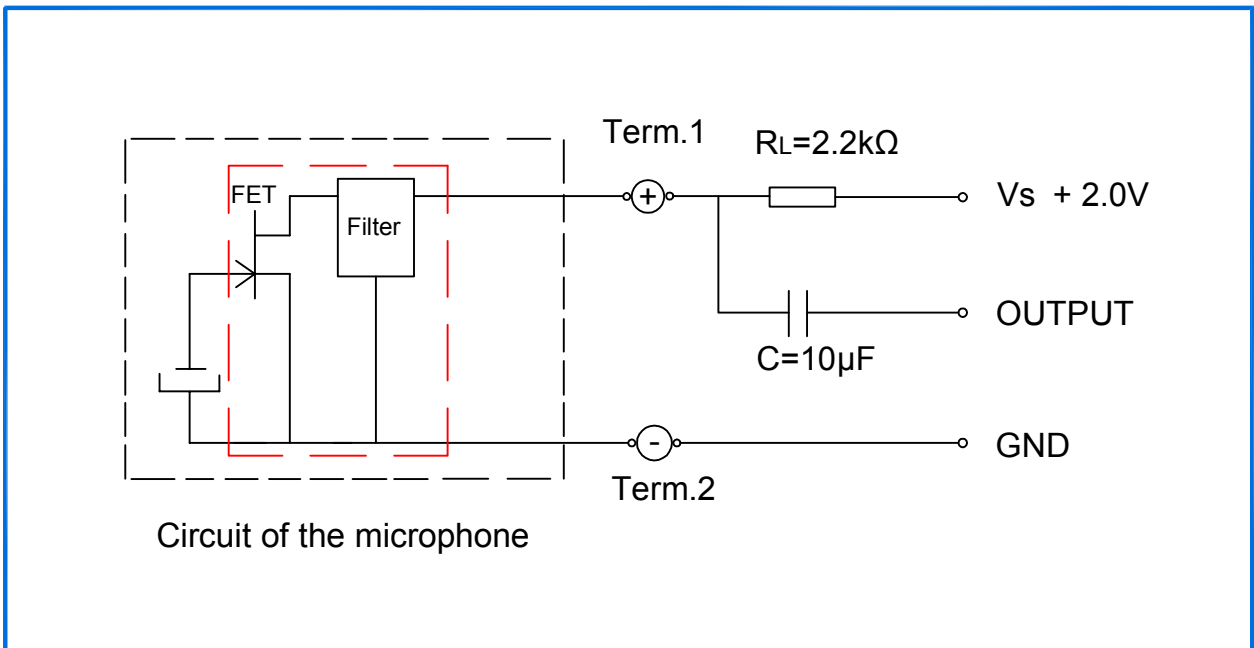
2 Electrical and Acoustical Characteristics

Item	Symbol	Test Conditions	Min	Typ	Max	Unit
Sensitivity	S	f=1kHz, Pin=1Pa	-45	-42	-39	dB 0dB=1V/Pa
Output Impedance	Zout	f=1kHz, Pin=1Pa			2.2k	Ω
Directivity	D(θ)	Omnidirectional				dB
Current Consumption	I				500	μA
S/N Ratio	S/N(A)	f=1kHz, Pin=1Pa A-Weighted Curve	58			dB
Decreasing Voltage Characteristic	ΔS	f=1kHz, Pin=1Pa Vs=2-1.5V	0		3	dB
Operating Voltage Range	Vs		1.1		5.0	V
Distortion	THD	f=1kHz, Pin=94dB			1	%
		f=1kHz, Pin=115dB			5	%
		f=1kHz, Pin=120dB			10	%

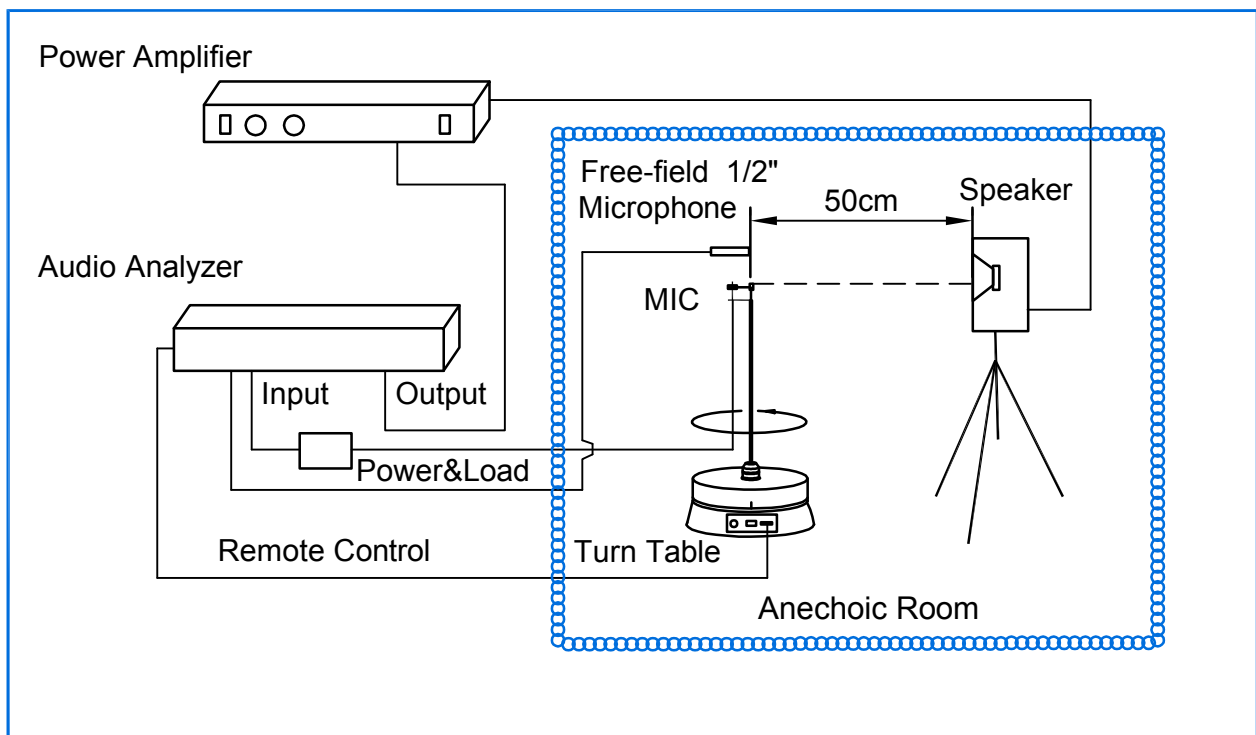
3 Frequency Response Curve and Limits



4 Measurement Circuit

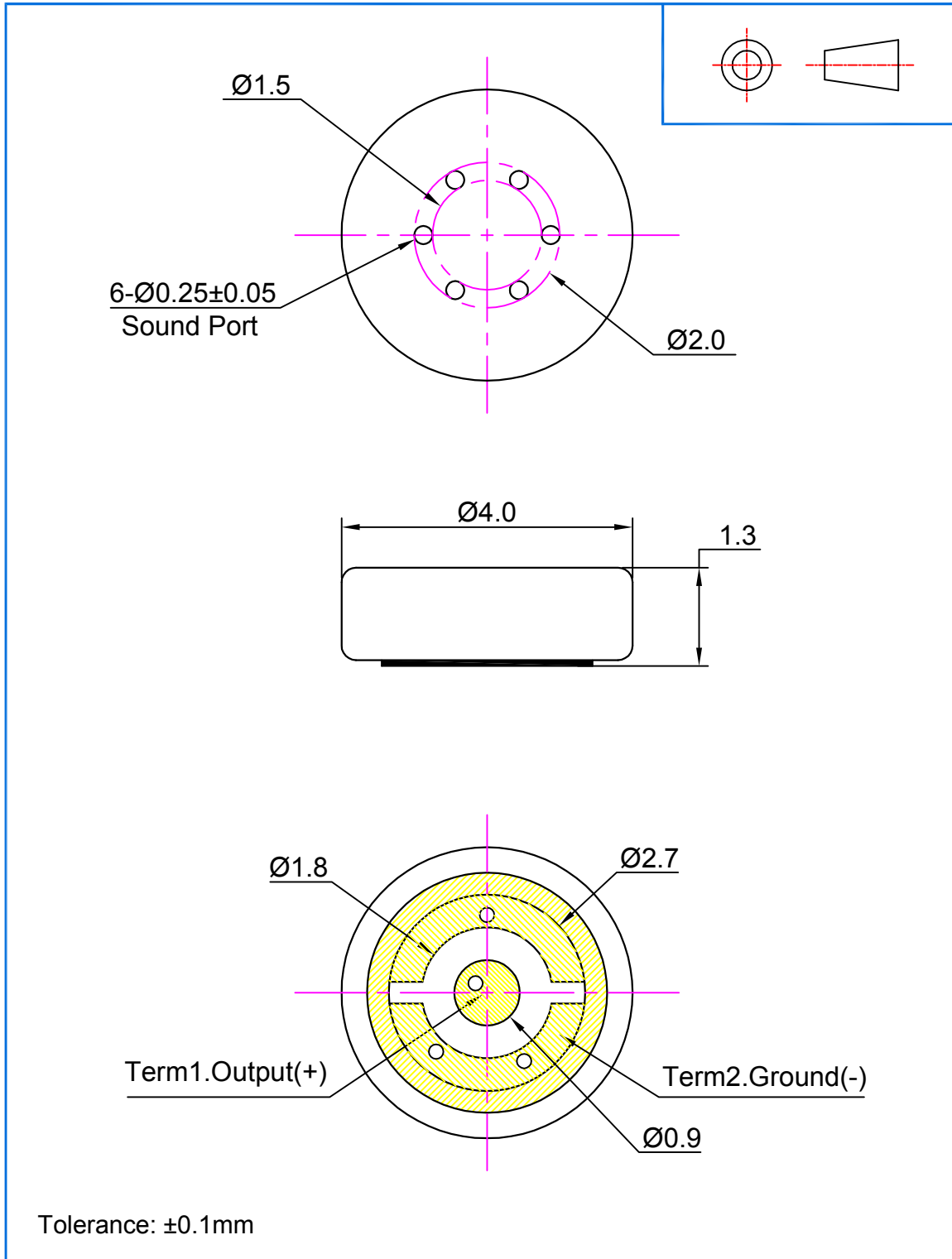


5 Test Setup Drawing



6 Mechanical Characteristics

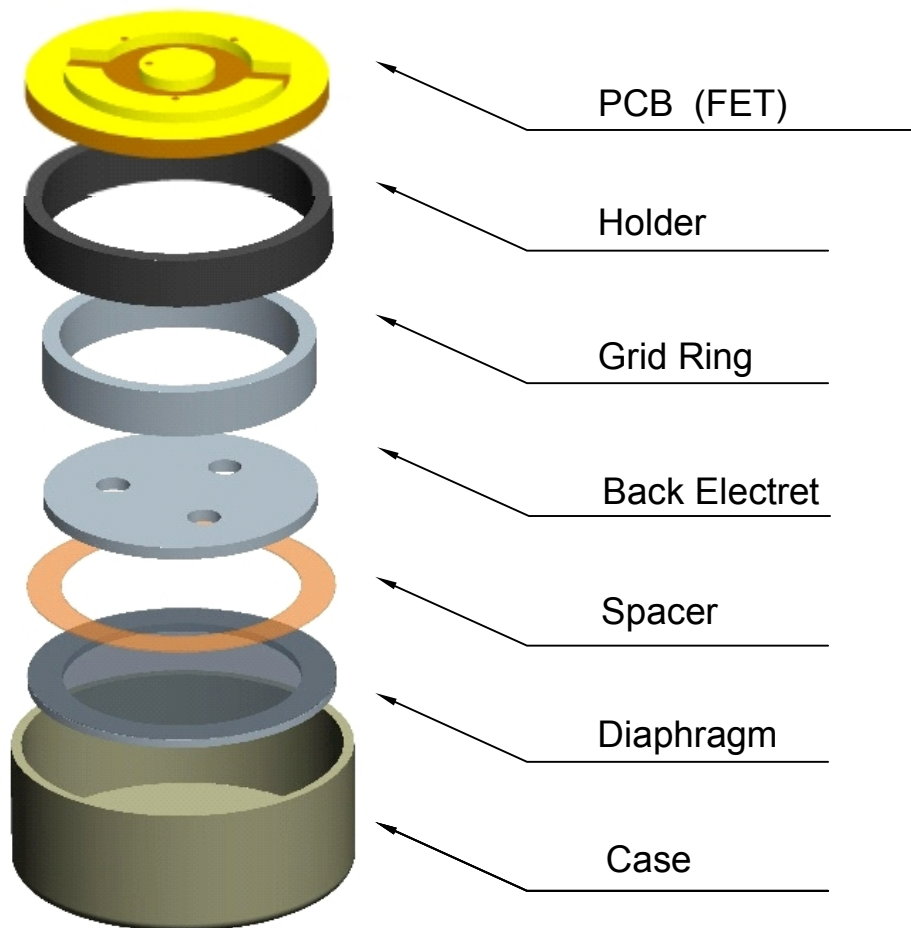
6.1 Appearance Drawing (Unit: mm)



6.2 Weight

The weight of the MIC is less than 0.2g.

7 Structure of SMD MIC



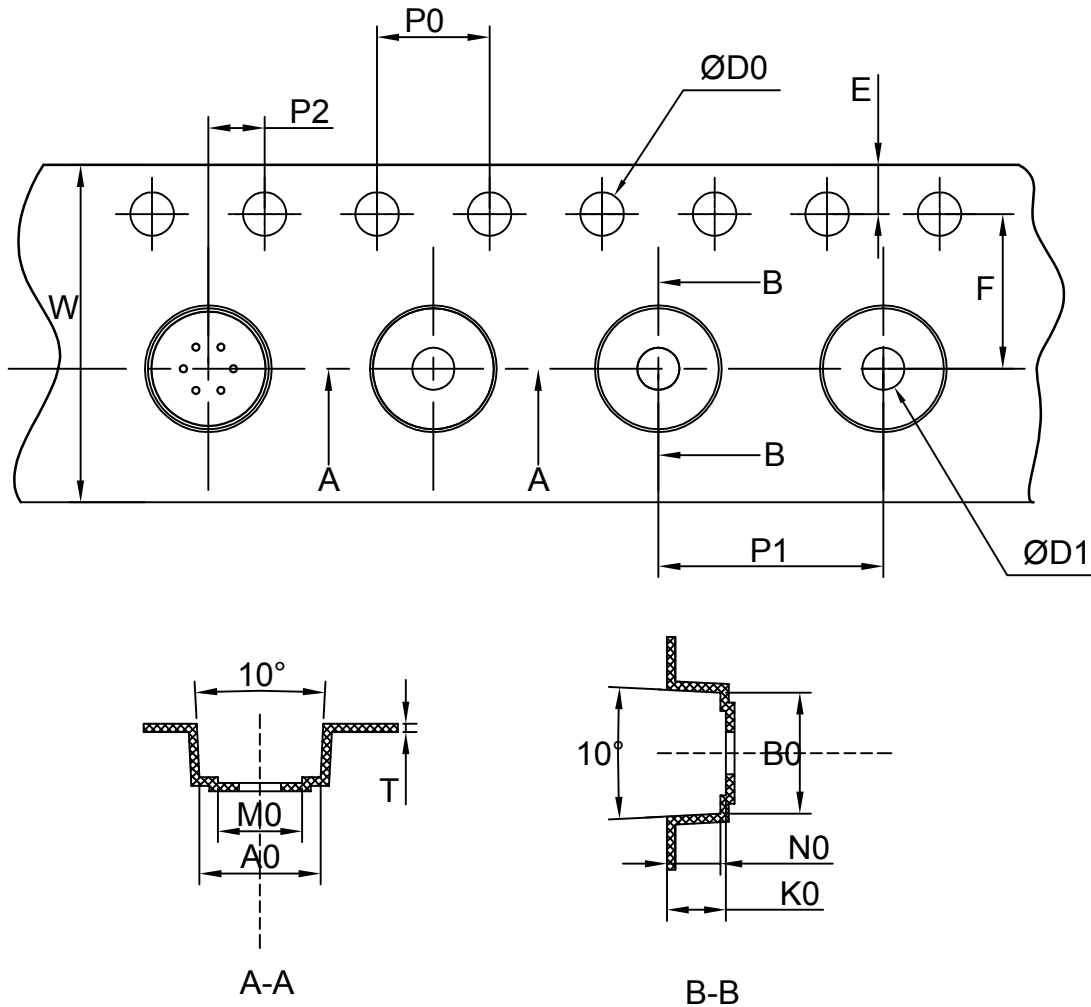
No.	Item	Qty.	Vendor	Material
1	PCB	1	KJ	FR-4
2	Holder	1	Yuyuan	HTN
3	Grid Ring	1	Yuyuan	Brass with nickel-plated
4	Back Electret	1	Yinhe	Stainless steel with PTFE
5	Spacer	1	Wanda+GoerTek	PI
6	Diaphragm	1	GoerTek	Stainless ring +PPS with nickel-plated
7	Case	1	ABE	Brass with nickel-plated

8 Reliability Test

<p>8.1 Vibration Test</p>	<p>To be no interference in operation after vibrations, 10Hz to 55 Hz for 1 minute full amplitude 1.52mm, for 2 hours at three axes in state of standard packing, sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C} \sim +35\text{ }^{\circ}\text{C}$, R.H 25%~75%)</p>
<p>8.2 Drop Test</p>	<p>To be no interference in operation after dropped to steel plate each one time from 1.5 meter height, 12 times, sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C} \sim +35\text{ }^{\circ}\text{C}$, R.H 25%~75%)</p>
<p>8.3 Temperature Test</p>	<p>a) After exposure at $+85\text{ }^{\circ}\text{C}$ for 200 hours, sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C} \sim +35\text{ }^{\circ}\text{C}$, R.H 25%~75%) b) After exposure at $-40\text{ }^{\circ}\text{C}$ for 200 hours, sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C} \sim +35\text{ }^{\circ}\text{C}$, R.H 25%~75%)</p>
<p>8.4 Humidity Test</p>	<p>After exposure at $+60\text{ }^{\circ}\text{C}$ and 90~95% relative humidity for 200 hours, sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C} \sim +35\text{ }^{\circ}\text{C}$, R.H 25%~75%)</p>
<p>8.5 Temperature Cycle Test</p>	<p>After exposure at $-40\text{ }^{\circ}\text{C}$ for 30 minutes, at $20\text{ }^{\circ}\text{C}$ for 10 minutes, at $+85\text{ }^{\circ}\text{C}$ for 30 minutes, at $20\text{ }^{\circ}\text{C}$ for 10 minutes, 5 cycles, sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C} \sim +35\text{ }^{\circ}\text{C}$, R.H 25%~75%)</p>
<p>8.6 Temperature Shock Test</p>	<p>After exposure at $-40\text{ }^{\circ}\text{C}$ for 60 minutes, at $+85\text{ }^{\circ}\text{C}$ for 60 minutes (change time 20 seconds), 32 cycles, sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C} \sim +35\text{ }^{\circ}\text{C}$, R.H 25%~75%)</p>
<p>8.7 ESD Shock Test</p>	<p>The microphone under test must be discharged between each ESD exposure without ground. (contact: $\pm 8\text{kV}$, air: $\pm 15\text{kV}$) There is no interference in operation after 10 times exposure.</p>
<p>8.8 Reflow Test</p>	<p>Adopt the reflow curve of item 11.3, after two reflows, sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C} \sim +35\text{ }^{\circ}\text{C}$, R.H 25%~75%)</p>

9 Package

9.1 Taping Specification



the dimensions as follows:

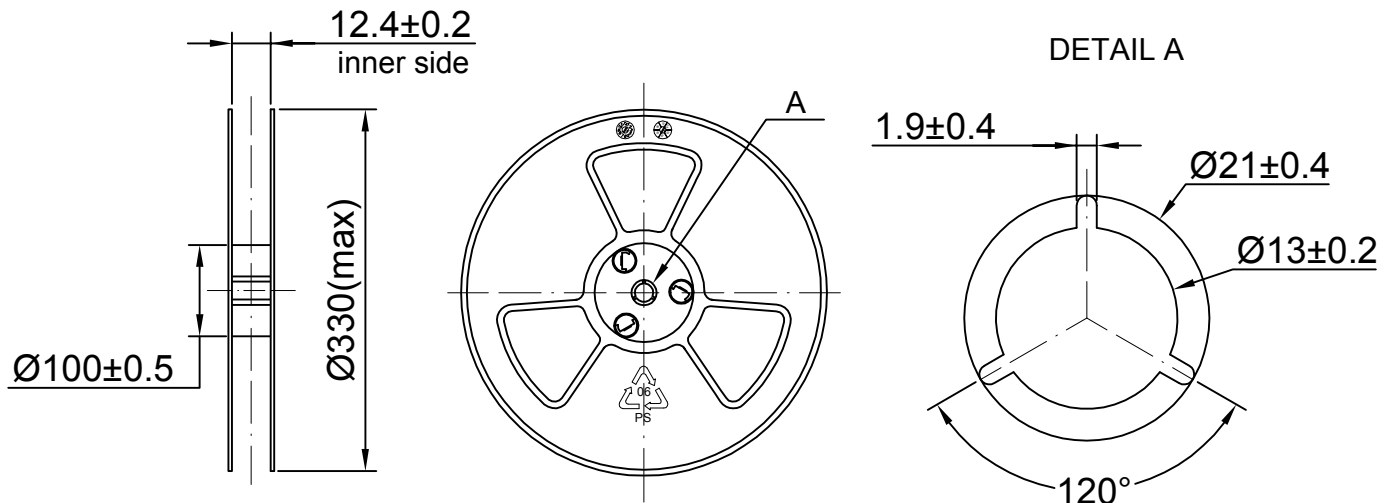
ITEM	W	E	F	ØD0	ØD1
DIM(mm)	12.0±0.30	1.75±0.10	5.50±0.05	1.50±0.10	1.55±0.10
ITEM	P0	10P0	P1	A0	B0
DIM(mm)	4.00±0.10	40.00±0.20	8.00±0.10	4.20±0.05	4.20±0.05
ITEM	K0	P2	T	M0	N0
DIM(mm)	1.70±0.10	2.00±0.05	0.35±0.05	3.00±0.05	1.50±0.1

9.2 Reel Dimension

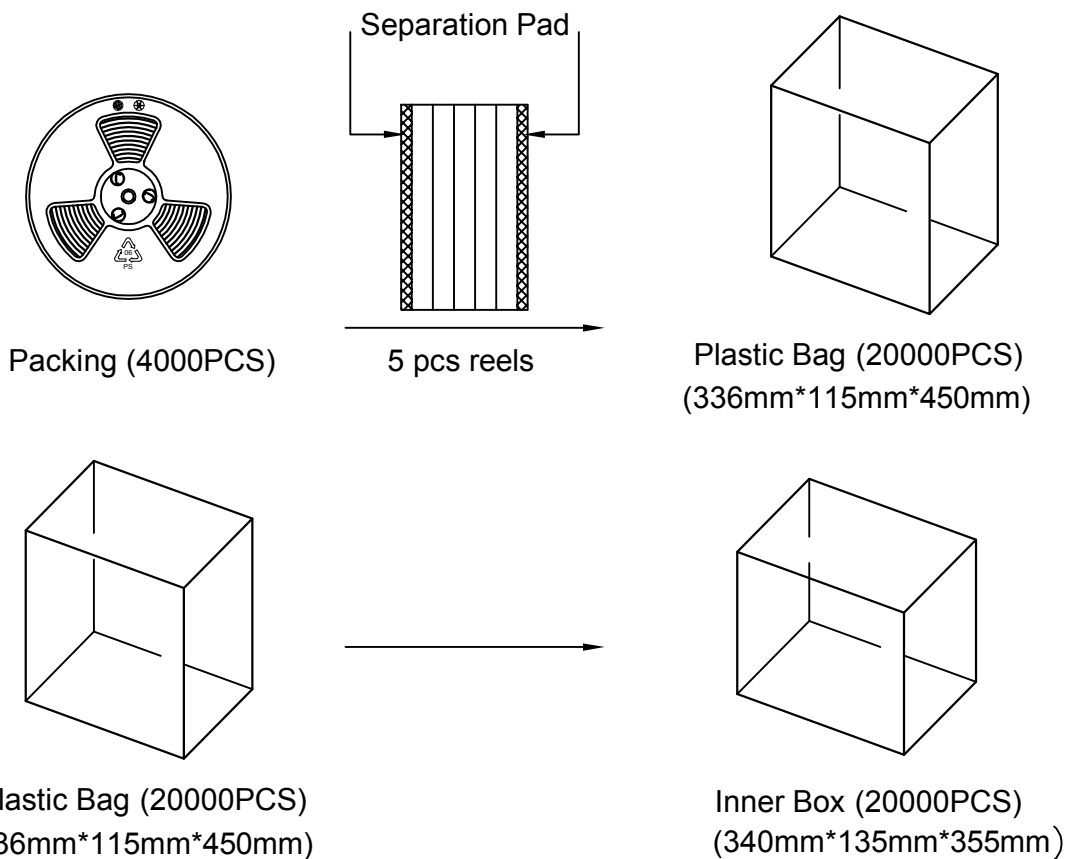
7 " reel for sample stage

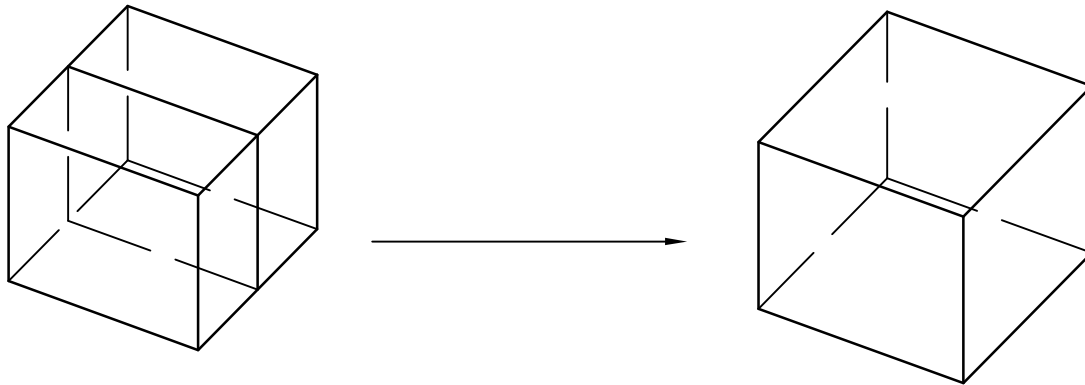
13 " reel will be provided for the mass production stage

The following is 13" reel dimensions (unit:mm)



9.3 The content of box(13" reel)



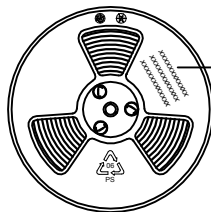


Two Inner Box(40000PCS)

Outer Box(40000PCS)
(370mm*300mm*390mm)

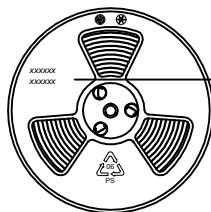
9.4 Packing Explain

9.4.1 The label content of the reel



the content including:
product type, Lot, customer P/N;
and other essential information such as Quantity,
Date etc.

9.4.2 The RoHS&HF Label



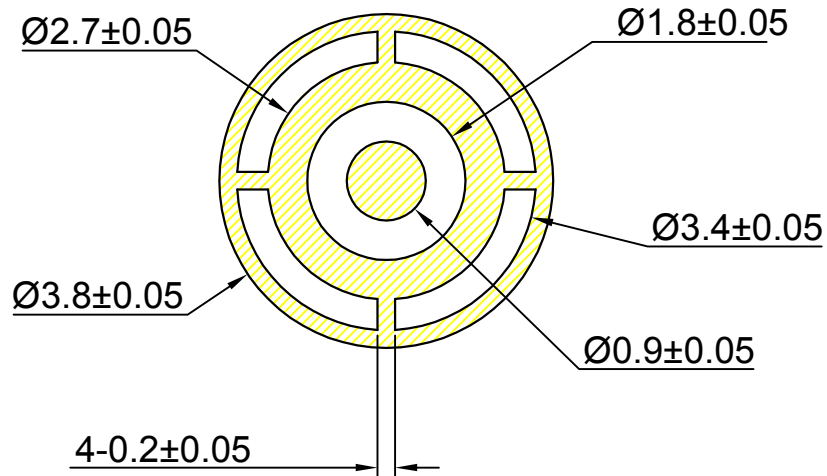
RoHS & HF
compliance mark

10 Stock and Transportation

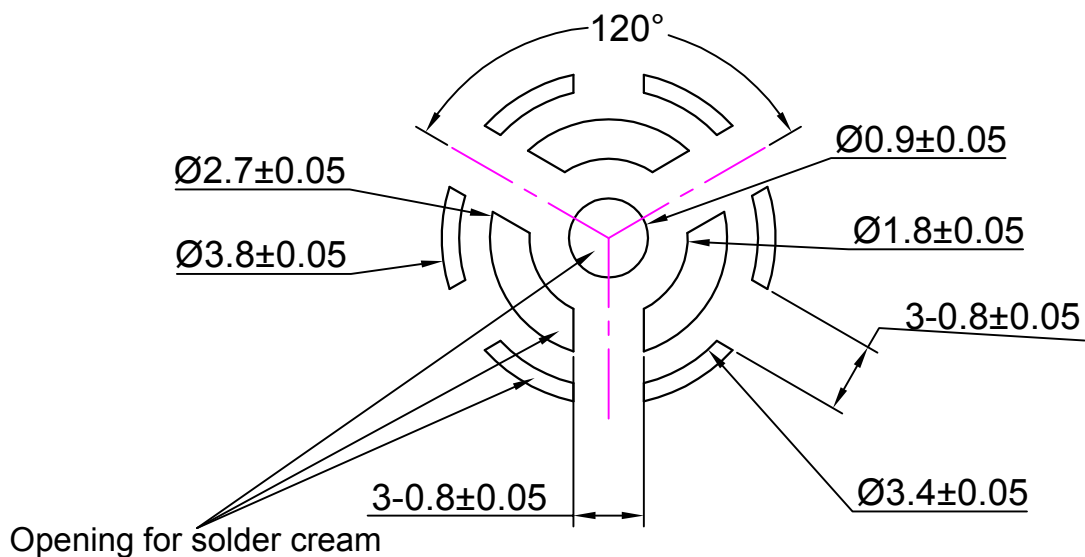
- 10.1 Keep ECM in warehouse with less than 75% humidity and without sudden temperature change, acid air, any other harmful air or strong magnetic field.
- 10.2 The ECM with normal pack can be transported by ordinary conveyances. Please protect products against moist, shock, sunburn and pressure during transportation.
- 10.3 Storage Temperature Range: -40 °C~+85°C
- 10.4 Operating Temperature Range: -30°C~+70°C

11 Land Pattern Recommendation (Unit: mm)

11.1 Soldering Surface - Land Pattern



11.2 Metal Mask Pattern



- thickness of metal mask: 0.1mm

12 Recommend Soldering

12.1 Soldering Machine Condition

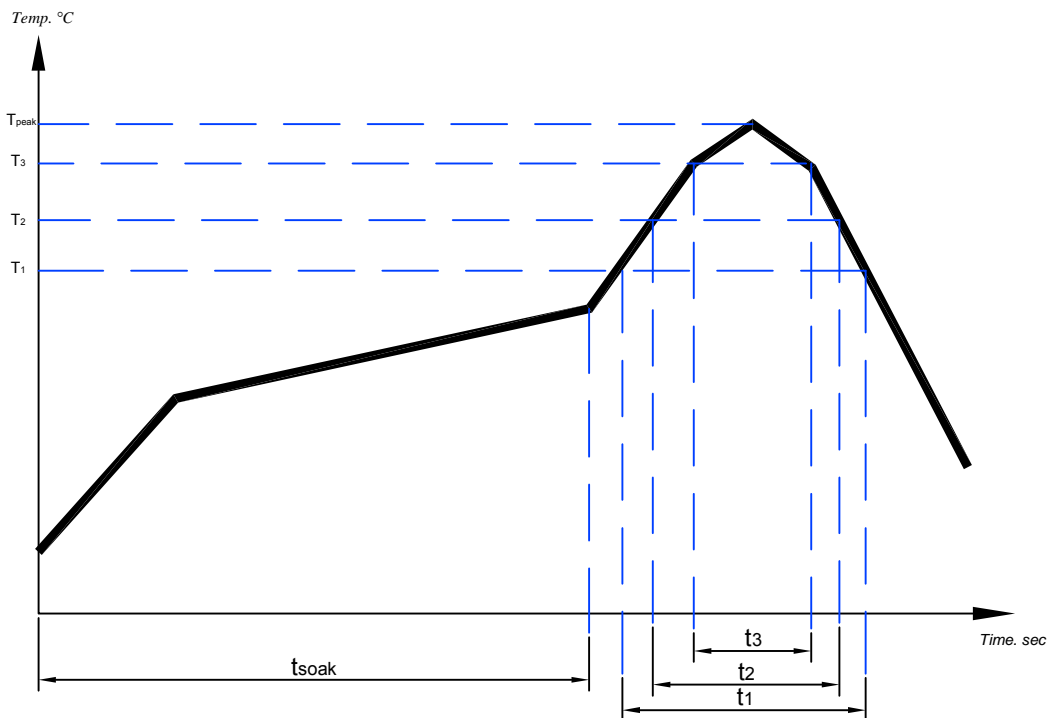
Temperature control	8 zones
Heater Type	Hot Air
Solder Type	Lead-free

12.2 The pattern of the nozzle



dimension of nozzle:504
external diameter: 1.5mm;
inside diameter: 1.0mm;
Pick up position:bottom border of microphone

12.3 Reflow Profile



Pb-free reflow profile requirements for soldering heat resistance

Parameter	Reference	Specification
Average Temperature Gradient in Preheating	---	2.5°C/s
Soak Time	t _{soak}	2-3 Minutes
Time Above 217 °C	t ₁	Max 60s
Time Above 230 °C	t ₂	Max 50s
Time Above 250 °C	t ₃	Max 10s
Peak Temperature In Reflow	T _{peak}	255 °C (-0/+5 °C)
Temperature Gradient In Cooling	---	Max -5 °C/s

When SMD MIC is soldered on PCB, the reflow profile is set according to solder paste and the thickness of PCB etc.

13 Cautions when using SMD MIC

13.1 X-ray inspection

The microphone should not be subjected to X-ray inspection. If it is absolutely necessary to do inspection using X-ray, the setting conditions with the following conditions:

Distance: >0.08meter;

Current: <0.080mA;

Time: <30s;

Voltage: <80kV.

13.2 Board wash restrictions

It is very important not to wash the PCBA after reflow process, or this could damage the microphone.

13.3 Nozzle restrictions

It is very important not to pull a nozzle over the post hole of the microphone. or this could damage the microphone.

13.4 Others restrictions

The pressure on the MIC shouldn't be more than 10N; The connecting between the institution and MIC should use rubber or Poron.

14 Output Inspection standard

output inspection standard is excuted according to <<ISO2859-1:1999>>.